Compact CMP System

**Features**

- Reasonable initial cost
- Small footprint
- High-performance CMP ➔ Know-how from mass production
- Flexible Customization up to user’s requirement ➔ From R&D, trial production to mass production

● 2”~12” polishing head available, multiple size of wafers are polishable in one system.
● Mounting of wafer loader enables full-automatic operation
● Mounting of cleaning unit enables precise cleaning
Air-float Head "Sylphide"

- Air film formation provides very uniform pressure distribution in the wafer plane.
- Possession of an airbag independent of an air film provides low-pressure stability.
- An independent retainer pressure airbag provides excellent edge profile control.
- One-touch replacement of retainer/membrane reduces downtime (see below).
- Addition of zone control function is available (optional).

The Cleaner can be separately purchased.